

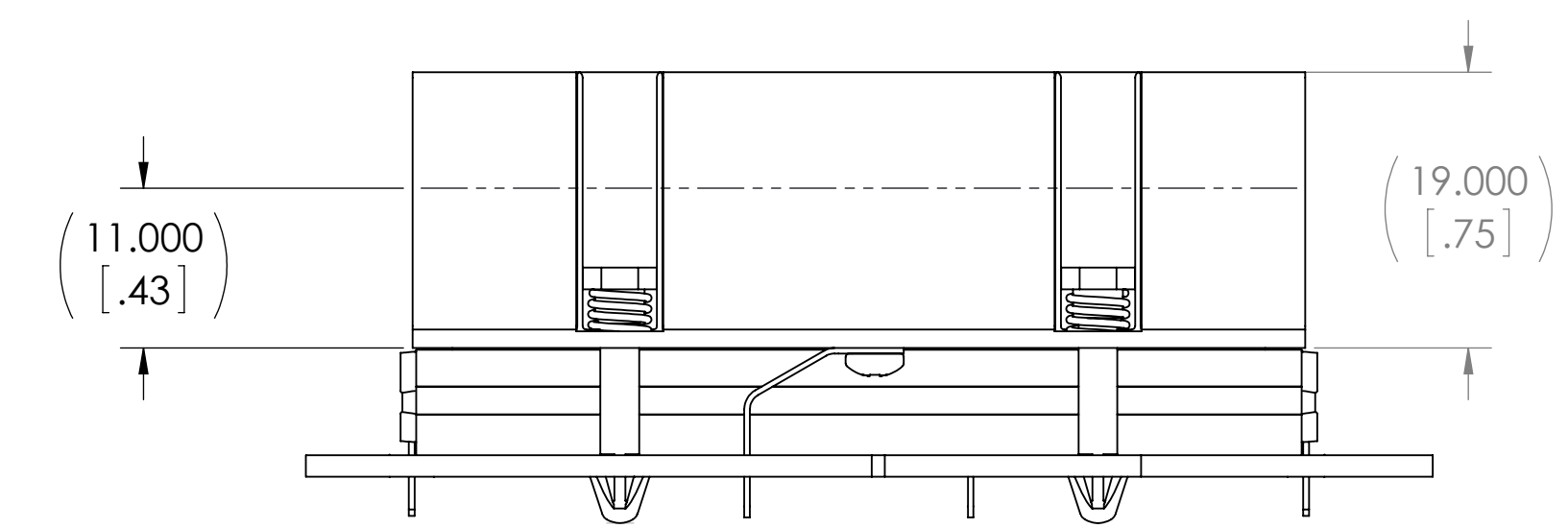
SEE NOTE 3
(4) PL.

SEE NOTE 3
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OPTIONAL
GROUNDING TABS (40247)
AND SCREWS (40327) (2) PL.
SEE NOTE 2 AND DRAWING 39983

6123 CHIP SHOWN HERE

OPTIONAL
GROUNDING TABS (40247)
AND SCREWS (40327) (2) PL.
SEE NOTE 2 AND DRAWING 39983



APPLIES TO BOTH 11MM AND 19MM HEATSINKS

ISO ASSY REF ONLY
LONGITUDINAL FLOW

ISO REF ONLY

THERMAL
INTERFACE
MATERIAL

GROUND TABS
AND SCREWS
TORQUE M2 SCREWS
TO 2 IN-LB (.2 Nm)

BOTTOM VIEW

X-FLOW (XF)
(HEAT SINK ONLY SHOWN)

LONGITUDINAL FLOW (LF)
(HEAT SINK ONLY SHOWN)

- NOTES:
- FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 39983.
 - THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C. SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW: (A) FOR HAND-SOLDERING ONLY. (B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

(A) PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS) ON PCB. WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.) HAND-SOLDER CHIP AND GROUNDING PINS.

(B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO VICOR TIM 40325 (PARKER CHOMERICS GEL8010) IS RECOMMENDED. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM 40325 TO THE TOP SURFACE OF THE CHIP, OR TO THE BOTTOM SURFACE OF THE HEATSINK. PLACE CHIP ON PCB AND TOP-SIDE HEATSINK ON CHIP. WITH A CUSTOM FIXTURE APPLY APPROX. 10 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND, WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
 - CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.
 - RoHS COMPLIANT PER CST-0001 LATEST REVISION.

PUSH-PIN FOR CHIP HEATSINK CHART

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
32434	WHITE	1.143 MM TO 1.422 MM [.045"] TO [.056"]	1.016 MM [.040"]	1.575 MM [.062"]
32435	BLACK	1.448 MM TO 2.311 MM [.057"] TO [.091"]	1.295 MM [.051"]	2.565 MM [.101"]
32436	BLUE	2.337 MM TO 3.023 MM [.092"] TO [.119"]	2.083 MM [.082"]	3.353 MM [.132"]
32437	GRAY	3.048 MM TO 3.607 MM [.120"] TO [.142"]	2.743 MM [.108"]	3.988 MM [.157"]

	HEATSINK TYPE	P/N HEATSINK ONLY	P/N HEATSINK W/ TIM ONLY	P/N HEATSINK, TIM AND GROUND TAB	P/N HEATSINK W/GROUND TAB ONLY
SOLDERING METHOD (SEE NOTE 2)	-	2(B) WITH VICOR 40325 THERMAL GEL	2(A) HAND SOLDER ONLY	2(A) HAND SOLDER ONLY	2(B) WITH VICOR 40325 THERMAL GEL
	4623	XF 11MM 39970 LF 11MM 39969 XF 19MM 40431 LF 19MM 40432	40492 40493 TBD TBD	40140 40144 40531 40532	40482 40483 TBD TBD
6123	XF 11MM 39972 LF 11MM 39971 XF 19MM 40406 LF 19MM 40407	40494 40495 TBD TBD	40141 40145 40533 40534	40484 40485 TBD TBD	

DRAWN BY Robert Wasik	DATE 07/24/2013	VICOR	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE: INCH / [MM]		APP DWG, CHIP PUSHPIN TOPSIDE HS, 6123, 4623	
TOLERANCES ARE: DECIMALS: .001" (0.025) ANGLES: ±1° XXX (X.X) = ±0.01 (0.25) X.XXX (X.XXX) = ±0.005 (0.127)		SIZE D	CAGE CODE 67131
THIRD ANGLE PROJECTION DO NOT SCALE DRAWING		DWG NO 40113	REV 1
SCALE 2:1		SHEET 1 OF 1	

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